

S Series Power MOSFET



RoHS
COMPLIANT
HALOGEN
FREE
Available

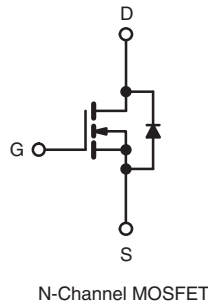
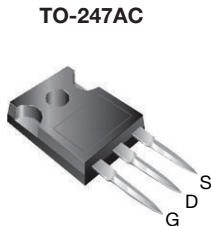
| PRODUCT SUMMARY | | |
|---|-----------------|-------|
| V_{DS} at T_J max. (V) | 650 | |
| $R_{DS(on)}$ max. at 25 °C (Ω) | $V_{GS} = 10$ V | 0.190 |
| Q_g max. (nC) | 98 | |
| Q_{gs} (nC) | 17 | |
| Q_{gd} (nC) | 25 | |
| Configuration | Single | |

FEATURES

- Generation one
- High E_{AR} capability
- Lower figure-of-merit $R_{on} \times Q_g$
- 100 % avalanche tested
- Ultra low R_{on}
- dV/dt ruggedness
- Ultra low gate charge (Q_g)
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- PFC power supply stages
- Hard switching topologies
- Solar inverters
- UPS
- Motor control
- Lighting
- Server telecom



| ORDERING INFORMATION | |
|---------------------------------|----------------|
| Package | TO-247AC |
| Lead (Pb)-free | SiHG22N60S-E3 |
| Lead (Pb)-free and Halogen-free | SiHG22N60S-GE3 |


| ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted) | | | | | |
|---|------------------|----------------|-------------|------|------|
| PARAMETER | SYMBOL | | LIMIT | UNIT | |
| Drain-Source Voltage | V_{DS} | | 600 | V | |
| Gate-Source Voltage | V_{GS} | | ± 30 | | |
| Continuous Drain Current | V_{GS} at 10 V | $T_C = 25$ °C | 22 | A | |
| | | $T_C = 100$ °C | 13 | | |
| Pulsed Drain Current ^a | I_{DM} | | 65 | | |
| Linear Derating Factor | TO-247 | | 2 | W/°C | |
| Single Pulse Avalanche Energy ^b | E_{AS} | | 690 | mJ | |
| Repetitive Avalanche Energy ^a | E_{AR} | | 25 | | |
| Maximum Power Dissipation | TO-247 | | P_D | 250 | W |
| Drain-Source Voltage Slope | $T_J = 125$ °C | | dV/dt | 37 | V/ns |
| Reverse Diode dV/dt ^d | | | | 5.3 | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | | -55 to +150 | °C | |
| Soldering Recommendations (Peak Temperature) ^c | for 10 s | | 300 | | |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- $V_{DD} = 50$ V, starting $T_J = 25$ °C, $L = 28.2$ mH, $R_g = 25$ Ω , $I_{AS} = 7$ A.
- 1.6 mm from case.
- $I_{SD} \leq I_D$, $dI/dt = 100$ A/ μ s, starting $T_J = 25$ °C.



| THERMAL RESISTANCE RATINGS | | | | | |
|----------------------------------|--------|------------|------|------|------|
| PARAMETER | | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | TO-247 | R_{thJA} | - | 62 | °C/W |
| Maximum Junction-to-Case (Drain) | TO-247 | R_{thJC} | - | 0.5 | |

| SPECIFICATIONS ($T_J = 25\text{ °C}$, unless otherwise noted) | | | | | | | |
|---|---------------------|---|---|---------------------------------------|-------|-----------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$ | | 600 | - | - | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ °C}, I_D = 1\text{ mA}$ | | - | 0.70 | - | V/°C |
| Gate-Source Threshold Voltage (N) | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | | 2.0 | - | 4.0 | V |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 20\text{ V}$ | | - | - | ± 100 | nA |
| | | $V_{GS} = \pm 30\text{ V}$ | | - | - | ± 1 | μA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$ | | - | - | 1 | μA |
| | | $V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ °C}$ | | - | - | 100 | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 10\text{ V}$ | $I_D = 11\text{ A}$ | - | 0.160 | 0.190 | Ω |
| Forward Transconductance ^a | g_{fs} | $V_{DS} = 50\text{ V}, I_D = 13\text{ A}$ | | - | 9.4 | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$ | | 562 | 2810 | 5620 | pF |
| Output Capacitance | C_{oss} | | | 296 | 1480 | 2960 | |
| Reverse Transfer Capacitance | C_{rss} | | | 6.6 | 33 | 66 | |
| Total Gate Charge | Q_g | $V_{GS} = 10\text{ V}$ | $I_D = 22\text{ A}, V_{DS} = 480\text{ V}$ | - | 75 | 110 | nC |
| Gate-Source Charge | Q_{gs} | | | - | 17 | - | |
| Gate-Drain Charge | Q_{gd} | | | - | 25 | - | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 380\text{ V}, I_D = 22\text{ A}, R_g = 9.1\text{ }\Omega, V_{GS} = 10\text{ V}$ | | - | 24 | 50 | ns |
| Rise Time | t_r | | | - | 68 | 100 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | - | 77 | 115 | |
| Fall Time | t_f | | | - | 59 | 90 | |
| Gate Input Resistance | R_g | | | $f = 1\text{ MHz}, \text{open drain}$ | | 0.13 | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode |  | - | - | 22 | A |
| Pulsed Diode Forward Current | I_{SM} | | | - | - | 65 | |
| Diode Forward Voltage | V_{SD} | $T_J = 25\text{ °C}, I_S = 22\text{ A}, V_{GS} = 0\text{ V}$ | | - | - | 1.2 | V |
| Reverse Recovery Time | t_{rr} | $T_J = 25\text{ °C}, I_F = I_S, di/dt = 100\text{ A}/\mu\text{s}, V_R = 25\text{ V}$ | | - | 462 | - | ns |
| Reverse Recovery Charge | Q_{rr} | | | - | 8.3 | - | μC |
| Reverse Recovery Current | I_{RRM} | | | - | 30 | - | A |

Note

a. $C_{oss\text{ eff.}}$ (TR) is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

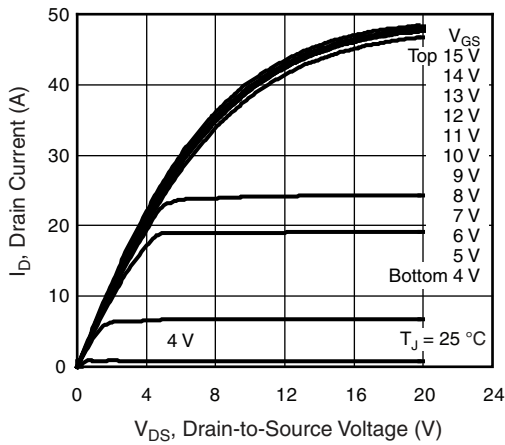


Fig. 1 - Typical Output Characteristics, $T_J = 25\text{ }^\circ\text{C}$

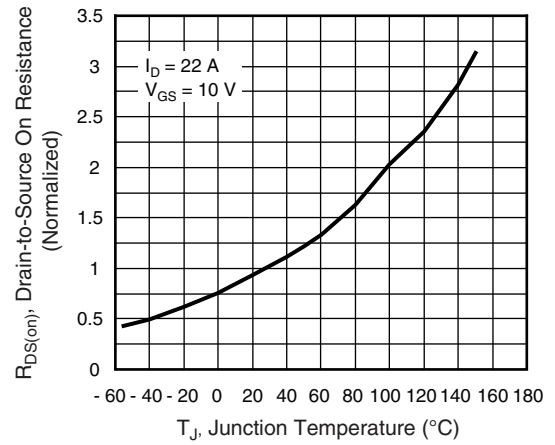


Fig. 4 - Normalized On-Resistance vs. Temperature

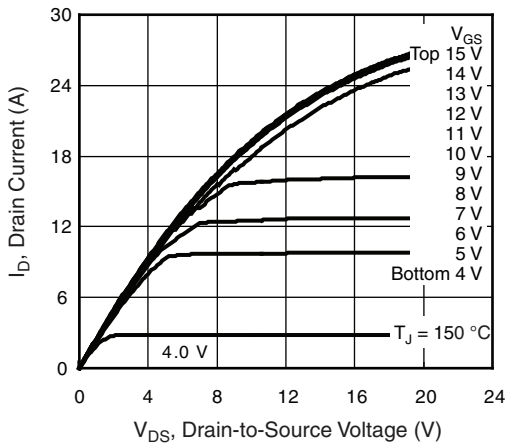


Fig. 2 - Typical Output Characteristics, $T_J = 150\text{ }^\circ\text{C}$

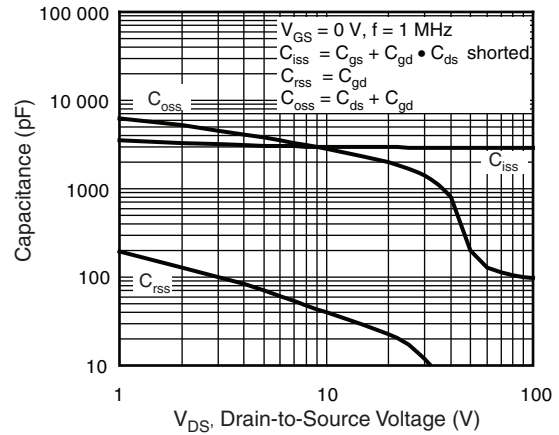


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

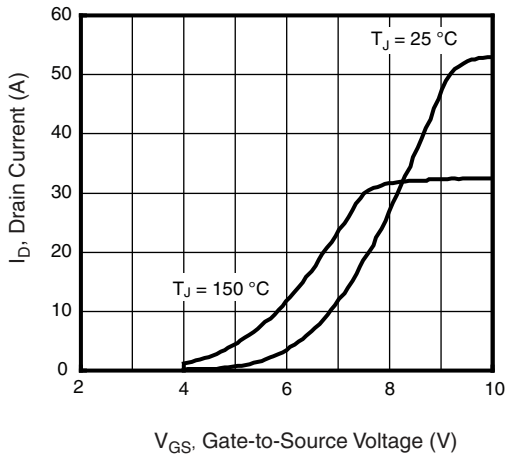


Fig. 3 - Typical Transfer Characteristics

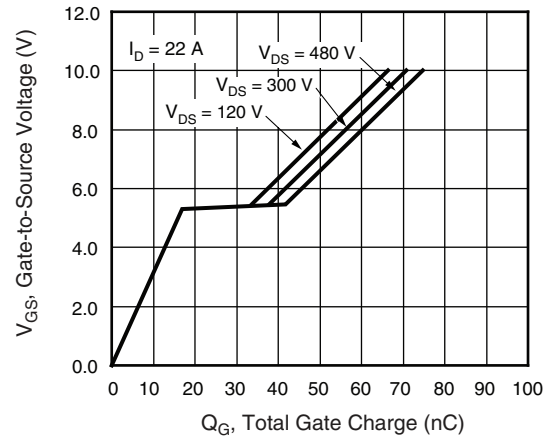


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

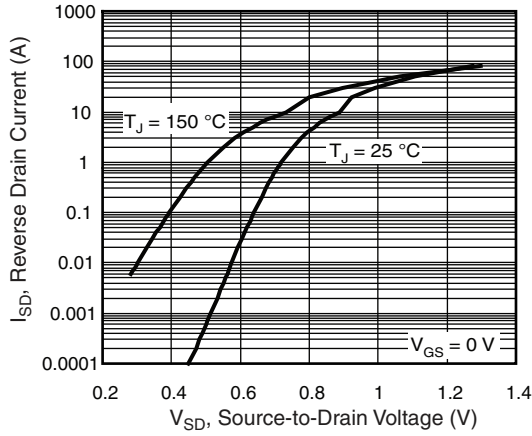


Fig. 7 - Typical Source-Drain Diode Forward Voltage

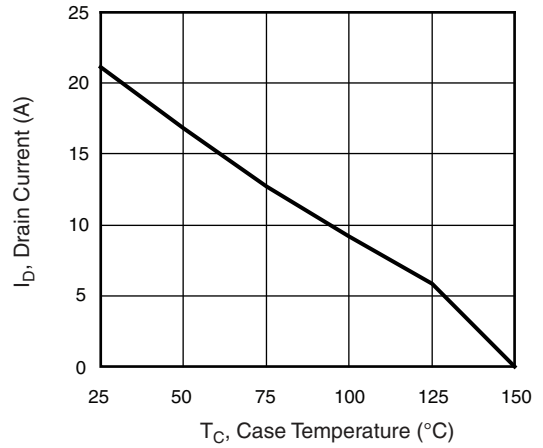


Fig. 9 - Maximum Drain Current vs. Case Temperature

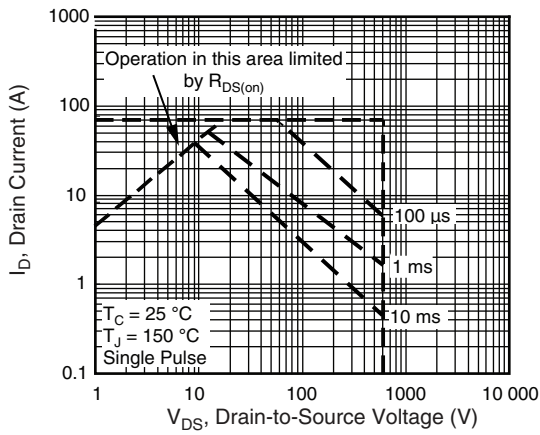


Fig. 8 - Maximum Safe Operating Area

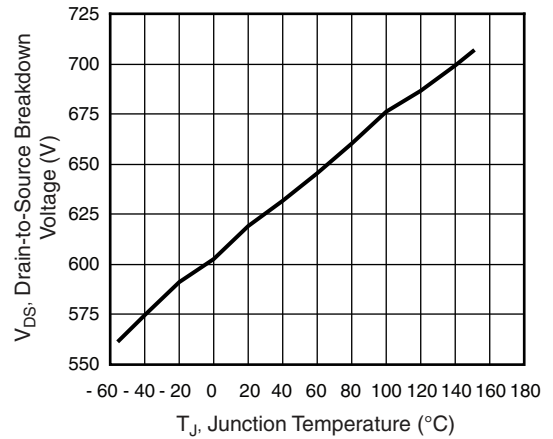


Fig. 10 - Drain-to-Source Breakdown Voltage

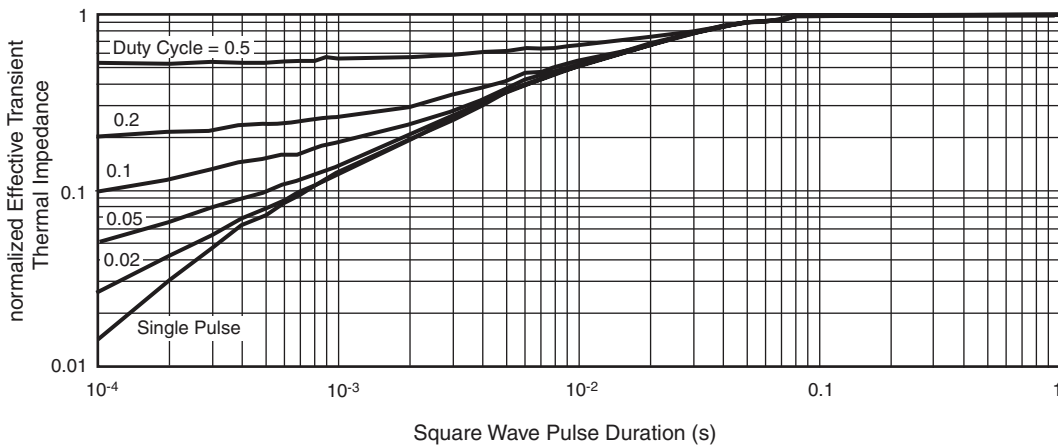


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

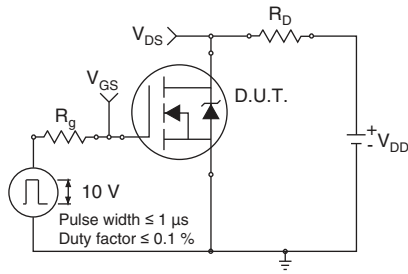


Fig. 12 - Switching Time Test Circuit

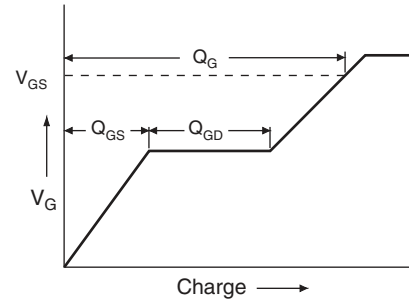


Fig. 16 - Basic Gate Charge Waveform

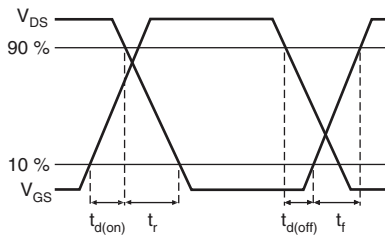


Fig. 13 - Switching Time Waveforms

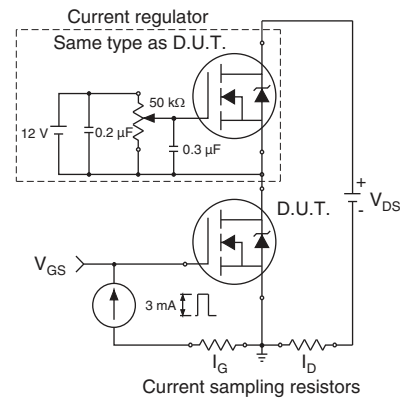


Fig. 17 - Gate Charge Test Circuit

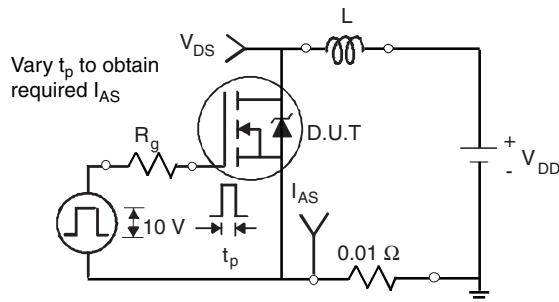


Fig. 14 - Unclamped Inductive Test Circuit

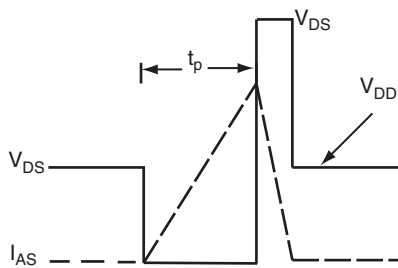
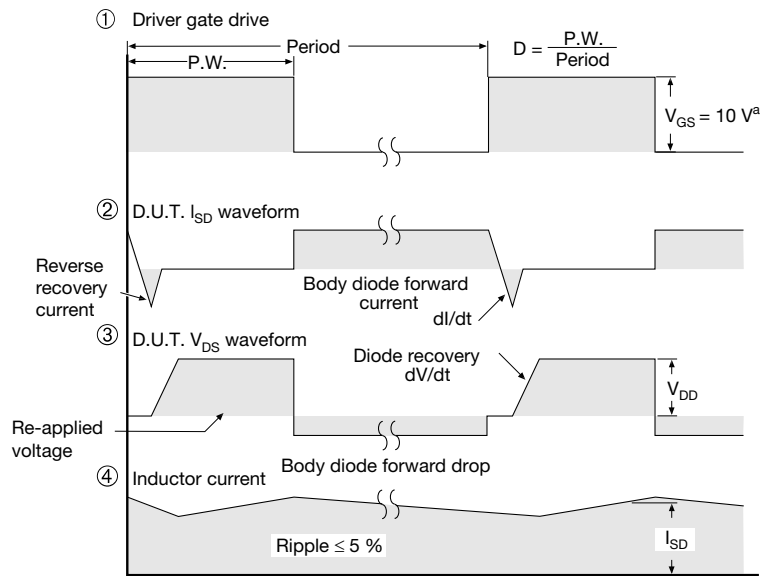
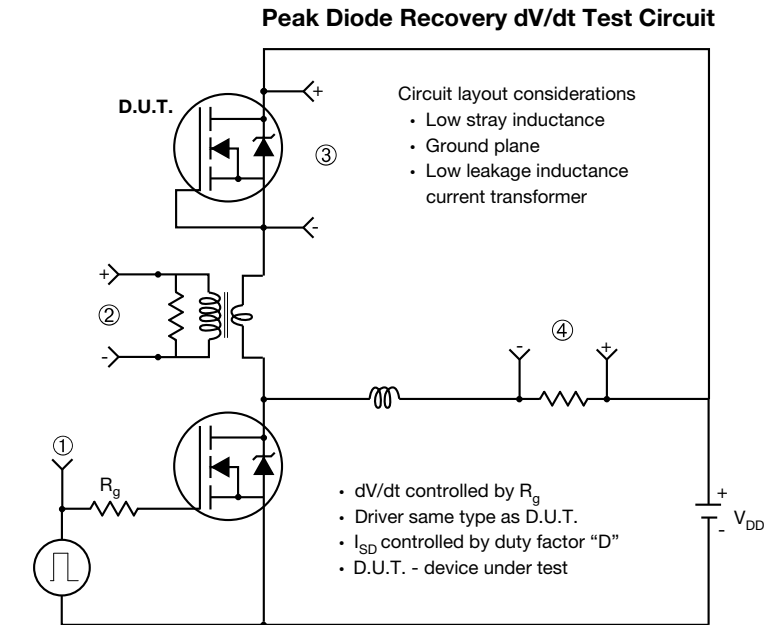


Fig. 15 - Unclamped Inductive Waveforms



Note
a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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